



MAX-PLANCK-INSTITUT FÜR PHYSIK

Operational Experience of the Belle II Pixel Detector

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VERTEX 2021, September 27th, 2021



SuperKEKB & Belle II

SuperKEKB

- Upgrade of existing KEKB accelerator.
- B factory: $E_{cm} = M_{Y(4S)} \approx 10.58 \text{ GeV}.$
- Target luminosity: 6 x 10³⁵ cm⁻² s⁻¹
 - Nano-beam technology and increased current.
 - Challenge: higher background.
- World record: 3.12 x 10³⁴ cm⁻² s⁻¹ @ June 2021.



Belle II

- Upgrade of Belle detector.
- Target: 50 ab⁻¹ by 2030.
- Totally ~213 fb⁻¹ of data until July 2021.
- Maximum trigger rate: 30 kHz.



Vertex Detector on Belle II

- Silicon Vertex Detector (SVD): [see Yuma Uematsu's talk about SVD]
 - 4 layers of 2-sided silicon strips.
 - $R \leq 140$ mm.
- Pixel Vertex Detector (PXD):
 - 2 layers of DEPFET sensors.
 - 8 inner ladders at radius 14 mm.
 - 12 outer ladders at radius 22 mm (only 2 ladders installed).
 - ~7.7 x 10⁶ pixels.
 - ~0.21% X₀ / layer material budget.



Scatter plot from data

VXD half shell





PXD Working Principle: DEPFET

- Depleted P-channel Field Effect Transistor (DEPFET) on top of fully depleted silicon bulk:
 - Fast charge collection (~ns).
 - Low power consumption.
 - High signal-to-noise ratio.
 - Thin sensors (75 um in active region).
- Working principle:
 - Collecting charges in the "internal gate".
 - Drain current modulated by collected charges.
 - Gate must be cleared after readout.
 - Internal amplification:

$$g_q = \frac{\partial I}{\partial q} \approx 500 \frac{pA}{e^-}$$



PXD Sensor / Module

- Sensor:
 - Self-supporting 75 um thin DEPFET active area.
 - Pixel size: 50x(55-85) um².
 - 250 x 768 pixels per sensor.
 - 40 sensors in total.
- Module:
 - DEPFET sensor with ASICs.
 - 6 switchers: row control, 4 rows per channel.
 - 4 DCD: 256 channel 8-bit ADC.
 - 4 DHP: data processing, trigger and timing.
 - 40 modules in total.
- Ladder:
 - Two modules glued to one ladder.
 - 20 ladders in total.
- Design: 1% occupancy (layer 1), 3% occupancy limit (DHP, DAQ, tracking).
- Cooling:
 - 2-phase CO₂ cooling for ASICs at the end of stave.
 - N₂ gas for sensor and switchers.
- Radiation hard sensor and ASICs up to expected lifetime, measured up to 266 kGy during irradiation campaign.



PXD DAQ

- PXD readout:
 - Rolling shutter readout mode.
 - Read 4-rows of pixels (1 switcher channel) at a time (~100ns).
 - Full integration time ~20 us.
- PXD has significant larger unfiltered raw data rate than other Belle II detectors:
 - Separate readout path.
 - Need to remove data that not belonging to tracks.
 - On High Level Trigger (HLT), Region of Interest (ROI) is calculated from track information.
 - 1/10 reduction rate.
 - Send ROIs back to PXD readout and select pixels within ROIs.
- Online selection has been tested but not turned on yet.







PXD Module Calibration

- Modules need characterization before installation.
 - Continuous optimization of working points during operation.
- Median drain current pedestals stored on DHP for zero suppression.
- Pedestal optimization on DCD:
 - Pedestal spreading compression via switchable offsets for input currents per pixel.
 - Noise reduction via Analog Common Mode Correction (ACMC).
 - Low noise < 1 ADU (~200 e⁻).



Calibrated Pedestals



Compro



Noise of 0.61 ADU

current



PXD Performance: Signal and Noise

- Most Probable Values (MPV) of cluster charge and SNR uniform over 24 ASIC combinations within one module.
- Signal to Noise Ratio ~ 30 to 50.
- Homogeneous noise and signal response across module matrix.





PXD Performance: Hit Efficiency

- Defined by hits found close to track intercepting points in modules.
- Influenced by tracking quality and alignment.
- Take only tracks with good tracking and $p_T > 1$ GeV/c.
- Bad switcher channels (4 rows each) degrade overall hit efficiency by ~3% (good regions ~ 98% hit efficiency).



PXD Performance: Resolution and Lifetime

- Vertex resolution with PXD is close to MC expectations.
 - d_0 resolution of 14.1 um (data), 12.5 um (MC).
- D lifetime measurement:
 - 4th Belle II physics paper, submitted to PRL, arXiv: 2108.03126.
 - Belle II proper time resolution ~2x better than Belle.
 - Precision better than all previous measurements and comparable with world average.
 - Vertex detectors played key role in this measurement.



 $\tau(D^0) = 410.5 \pm 1.1 \text{ (stat)} \pm 0.8 \text{ (syst) fs}$ $\tau(D^+) = 1030.4 \pm 4.7 \text{ (stat)} \pm 3.1 \text{ (syst) fs}$ World Average (410.1 ± 1.5) fs (1040 ± 7) fs



PXD Operation

- In general, PXD operation is stable for 2020/2021.
 - There are still several challenges for operation.
- Due to COVID-19, limited local PXD manpower in KEK.
 - Most of the PXD expert shifts are done in remote.
- Various automations to reduce the load of the shifters.
- New people are on boarding to the PXD group, for operation and R&D, even on the hardware side.

PXD Operation: Beam Loss Events

Beam loss event on May 10th ,2021:

- Not the first of such incidents, but the most serious one for the damage of a single module.
- Partial damage of PXD, diamond sensor readout and collimator.
- The reason is not fully clear.
- Not always detected early enough to safely dump beams before damage happens.
- Impact on PXD:
 - Large instant radiation dose.
 - Permanent damage: new dead switcher channels (unexpected behavior).

R&D to understand the mechanism of switcher damage:

- Radiation test at MAMI @ Mainz.
- Damage effect reproduced during tests.
- Discussion to continue tests at MAMI.



Damaged collimator jaws





PXD Operation: Mitigation for Beam Loss Events

- Several systems to detect beam disturbance and issue beam abort signal:
 - Diamond sensors on the beam pipe.
 - Beam loss monitors along the rings.
 - Others.
- Early detection of beam abort with CLAWS:
 - Scintillator Light and Waveform Sensors.
 - Close to interaction point.
 - Faster to detect and issue beam abort signal.
 - Speed up abort process time by ~10us (about one revolution of the beam).
 - Turned on for beam abort since end of May 2021.
- Reduce beam dump time on accelerator side.
- PXD emergency power off:
 - $O(100 \text{ms}) \rightarrow O(100 \text{us}).$
 - Tests still ongoing.
 - Could also harm on its own.



PXD Operation: Radiation Effect (Threshold Shift)

- X-ray radiation campaign @ 266 kGy:
 - Oxide damage causes shift of MOSFET threshold voltages.
 - Threshold voltage shift can be compensated by adjustment of gate voltage.
- Integrated dose in PXD:
 - Rough estimate < 20 kGy until end of 2020.
 - More precise measurements for 2021 in progress.



Source Current

Gate Voltage

PXD Operation: Radiation Effect (HV Current)

- HV is the depletion voltage of the DEPFET sensor.
- Increased HV currents of some modules:
 - Some of them reached power supply limits.
 - Can't reach set voltage: worse SNR and efficiency.
- Recovery observed during (beam off / HV on) and (beam on / HV off) times.
- X-ray irradiation campaign to investigate the effect:
 - Reproduced the increasing HV current w/ irradiation and annealing effect w/o irradiation.
 - Saturation of HV current at certain dose of radiation.
- Mitigation by modifying PS units to higher HV current limits.
 - HV current limit: 1.4 mA \rightarrow 2.8 mA \rightarrow 5 mA \rightarrow 14 mA
 - Part of the PS units modified in parallel to the data taking.
 - Remaining units have been modified to 14mA HV current limit during summer shutdown.
- Interpretation: charge-up effect at handle wafer bond oxide and avalanches at bulk.



PXD Operation: Backgrounds

- Single-beam backgrounds:
 - Touschek scattering: scattering of particles within a bunch.
 - Beam-gas scattering: Coulomb scattering and Bremsstrahlung (scattering off gas molecules).
 - Injection background: continuous injection of charge into beam bunch.
 - Synchrotron radiation.
- Luminosity backgrounds:
 - Two-photon background.
- Background effects:
 - Deteriorate performance (fake hits).
 - Contributes to occupancy (especially during injection).
 - Maximum occupancy 3%: at which the ASICs can't handle the high data rate.
 - Irradiation to sensors: aging or damages.





PXD Operation: Injection Backgrounds

- Continuous injection in SuperKEKB:
 - Top-up injection rate up to 50 Hz.
 - At design luminosity, beam lifetime is ~few minutes.
 - Injected bunches produce high backgrounds. Damping takes a few ms.
 - Use trigger veto to avoid noise:
 - full veto for all Belle II detectors.
 - gated veto for all except PXD due to long integration time (20 us).
- Elevated PXD occupancy after full veto for a few us:
 - Injection spikes can saturate PXD readout and cause partial data loss.
 - In 2021, the ratio of partial data loss is far from being critical (in subper mille level).
 - In the future, to reduce data loss, gated mode can be used to blind PXD when injected bunches passing by.







PXD Operation: SR Background

- IR region is designed to avoid direct SR photons hitting central beam pipe
- Observed large SR background:
 - Happened in –x modules after change of optics.
 - Dominated by secondary photons
 - Appear during HER injections with clear time structure
 - Origin: back-scattering photons from SR fan hitting +x edge of Ti beam pipe
- Effects on PXD:
 - Highly localized hit density
 - Inhomogeneous module irradiation
 - Deterioration of clustering and tracking
- Mitigation:
 - Small modification of HER beam orbit
 - New beam pipe with additional gold plating to be installed with PXD 2022 update.









PXD2022

PXD remains incomplete:

- Only 10/20 ladders installed:
 - Layer 1 is full with 8 ladders.
 - Layer 2 only has 2 ladders out of 12.
- Good vertexing performance so far, but not guaranteed for higher luminosity.

Ongoing efforts to build complete PXD:

- Same technology but improved manufacturing process.
- Module production & HS assembly & testing ongoing.
- PXD2 to be installed during next long shutdown 2022.





Summary

- PXD is working well since the start of Belle II data taking in 2019.
- The performance of PXD is excellent.
- Superior lifetime resolution compared to Belle/BaBar as demonstrated by the D lifetime measurement.
- There are damaged switcher channels due to beam loss events.
- Efforts have been made to automate the operation for reducing shifters' load.
- Full PXD detector:
 - Production, testing and assembly is ongoing.
 - Planned installation in 2022.

Backup

PXD Readout and Control

- Rolling shutter readout mode with low power consumption:
 - Signal read gate by gate.
 - Each gate consists of 4 rows.
 - Gate is cleared after reading.
 - Read-clear cycle for each gate is ~100ns.
 - Full integration time ~20 us (1 "frame").
 - ~2x SuperKEKB revolution time (~10 us).
- Sampling by DCD: drain currents measured once.
- Pedestal correction and zero suppression on DHP.
- Event building and trigger handling on DHH.
- ROI selection on ONSEN.
- Filtered data transferred to Belle II DAQ for further processing and storage.



PXD Assembly & Installation in 2018

PXD assembly at KEK:

- Assemble mechanical ladder frame SCB.
- Provide cooling via 2-phase CO_2 and forced N_2 flow. Installation to Belle II in late 2018:
- SVD + PXD + BP marriage.
- VXD installation into Belle II.







PXD Operation: Gated Mode

- Gated mode can blind PXD modules when noisy bunches pass.
 - To protect PXD from the noises from the injected bunches.
 - The voltages applied on the DEPFET sensors are changed.
 - Newly created charges are not collected.
 - Charges at internal gate are preserved.
 - Gate twice per readout frame.
- Challenges:
 - Switching into gated mode results in pedestals fluctuations, produce noise on their own.
 - Synchronization with injections.
 - Optimizing module parameter for GM.
- Currently not ready for regular gated mode operation.

